

# A FULLY 3-D BIE EVALUATION OF THE RESISTANCE AND INDUCTANCE OF ON-BOARD AND ON-CHIP INTERCONNECTS

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# OUTLINE

- Motivation
- Proposed technique
- Examples
- Conclusions



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### Smaller & faster electronics

Increasing complexity, functionality, signal integrity, power constraints, ...

### New solutions such as 3-D ICs













### Many challenges

Heat distribution



Signal integrity (crosstalk, dispersion, distortion, ...)



### Rigorous modeling increasingly essential !





# PROBLEM STATEMENT

- Finite conductivity, skin effect, proximity effect
  - difficult to model broadband
- Solved in 2-D [1, 2] using a Dirichlet-to-Neumann operator
- Open question in 3-D

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- Recently proposed for 3-D cylinders and cuboids [3, 4]

[1] D. De Zutter and L. Knockaert, IEEE MTT, vol. 53, pp. 2526-2538 (2005) [2] T. Demeester and D. De Zutter, IEEE MTT, vol. 56, pp. 1649-1660 (2008) [3] M. Huynen, M. Gossye, D. De Zutter and D. Vande Ginste, IEEE AWPL, vol. 16, pp. 1052-1055 (2017) [4] M. Huynen, D. De Zutter and D. Vande Ginste, accepted for IEEE MWCL



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**Original situation** 



Equivalent situation

Electric field integral equation

$$\mathbf{e}_0 - \mathbf{e}_i = -j\omega\mathbf{a} - \nabla\phi$$

Test and basis functions

$$\begin{cases} \mathbf{j}_s \\ \mathbf{e}_0 \end{cases} = \sum_m \begin{cases} I_m \\ E_{0,m} \end{cases}$$



















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### POSED TECHNI JE

 $\mathbf{e}_0 - \mathbf{e}_i = -j\omega\mathbf{a} - \nabla\phi$ 

### Discretization



### Via partial integration:









$$\overline{\overline{G}}\mathbf{E}_0 - \mathbf{V}_i = -j\omega\overline{\overline{L}}\mathbf{I} + \mathbf{V}^+$$

### **Circuit interpretation**







### Still 2 sets of unknowns:

nec

### 3-D Dirichlet-to-Neumann operator $\mathcal{D}_k$ [3, 4]





[3] M. Huynen, M. Gossye, D. De Zutter and D. Vande Ginste, IEEE AWPL, vol. 16, pp. 1052-1055 (2017) [4] M. Huynen, D. De Zutter and D. Vande Ginste, accepted at IEEE MWCL

$$\mathbf{u}_n imes \mathbf{h} = \mathcal{D}_{k_0} \mathbf{e}^t$$





### FCHN JE













### SED TECHNI JE

$$\left(\overline{\overline{G}}\,\overline{\overline{Y}}^{-1}\,\overline{\overline{G}}\right)\mathbf{I} - \mathbf{V}_i = -j\omega\overline{\overline{L}}\mathbf{I} + \mathbf{V}^+$$

**Circuit interpretation** 



- I







### Only 1 set of unknowns left:

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# **EXAMPLE: PARALLEL CONDUCTORS**

### Normalized resistance = total resistance (3-D) / length





# **EXAMPLE: PARALLEL CONDUCTORS**



[1] D. De Zutter and L. Knockaert, IEEE MTT, vol. 53, pp. 2526-2538 (2005)







# **EXAMPLE: RIGHT-ANGLED CORNER**









### cuboid

# **EXAMPLE: RIGHT-ANGLED CORNER**

### right-angled corner









# **EXAMPLE: RIGHT-ANGLED CORNER**

### Resistance

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### Resistance





[5] U. R. Patel, S. V. Hum and P. Triverio, IEEE 21st Workshop on SPI, pp. 1-4 (May 2017) unec





[5] U. R. Patel, S. V. Hum and P. Triverio, IEEE 21st Workshop on SPI, pp. 1-4 (May 2017) unec

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### Resistance





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### Inductance





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# CONCLUSIONS

### Novel 3-D interconnect modeling tool

- Based on BIE (without volume meshing)
- Fully 3-D differential surface admittance operator
- $\Rightarrow$  Rigorous approach for skin effect, proximity effect, etc. in 3-D interconnects
- Validation and applications
  - Application to PCB and IC interconnect structures
  - Accurate modeling of corners
  - Broadband extraction of R- and L-parameters
  - Thoroughly compared to industry standards





# FURTHER READING

### 2-D:

D. De Zutter and L. Knockaert, "Skin effect modeling based on a differential surface admittance operator", IEEE MTT, vol. 53, pp. 2526-2538 (2005)

T. Demeester and D. De Zutter, "Quasi-TM Transmission Line Parameters of Coupled Lossy Lines Based on the Dirichlet to Neumann Boundary Operator", IEEE MTT, vol. 56, pp. 1649-1660 (2008)

### 3-D:

M. Huynen, M. Gossye, D. De Zutter and D. Vande Ginste, "A 3-D Differential Surface Admittance Operator for Lossy Dipole Antenna Analysis", IEEE AWPL, vol. 16, pp. 1052-1055 (2017)

M. Huynen, D. De Zutter and D. Vande Ginste, "Boundary integral equation study of the influence of finite conductivity on antenna radiation using a 3-D differential surface admittance operator", ACES Symposium - Italy (March 2017)

M. Huynen, D. De Zutter and D. Vande Ginste, "*Rigorous full-wave resistance and inductance computation of 3-D interconnects*", accepted at IEEE MWCL





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